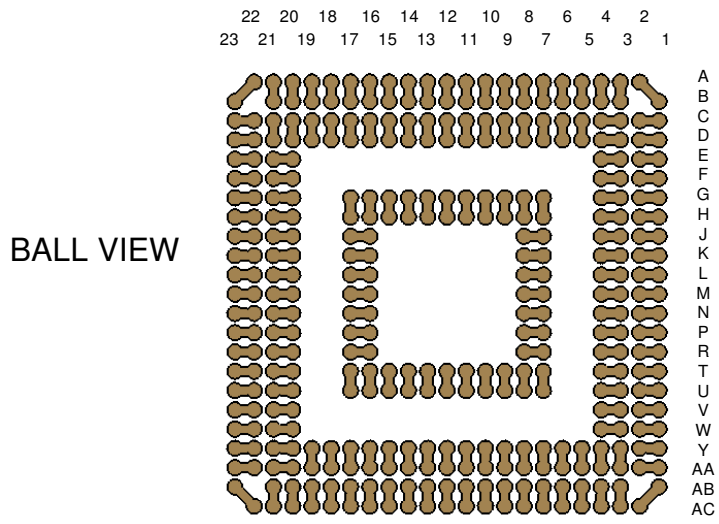


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.18mm.
 - 4) NON-SOLDER MASK DEFINED PAD (NSMD) OPENING: 0.20mm.
 - 5) PAD Cu DIAMETER: 0.24mm.
 - 6) SUBSTRATE MATERIAL: BT. HL832NX-A
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

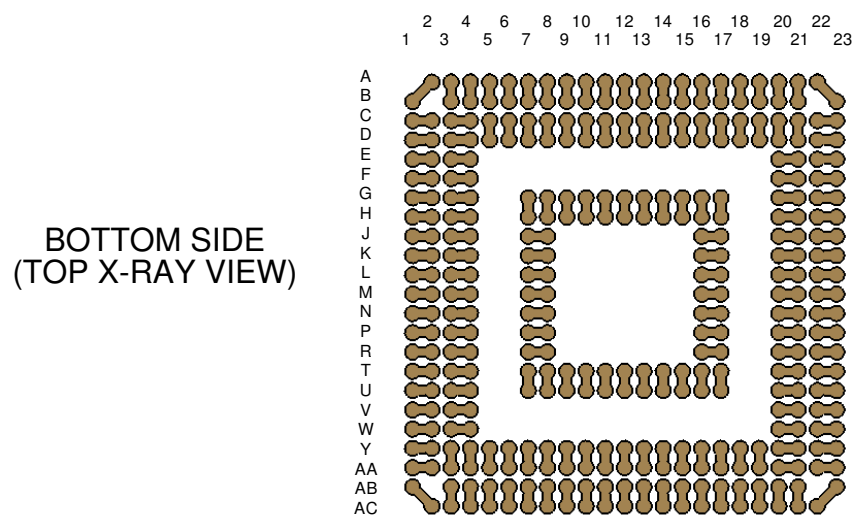
SECTION A-A

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA368T.3C-DC238D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA368T.3C1-DC238D	Sn98.5/Ag1.0/Cu0.5	YES	YES	YES
BGA368T.3-DC238D	Sn63/Pb37	NO	NO	YES

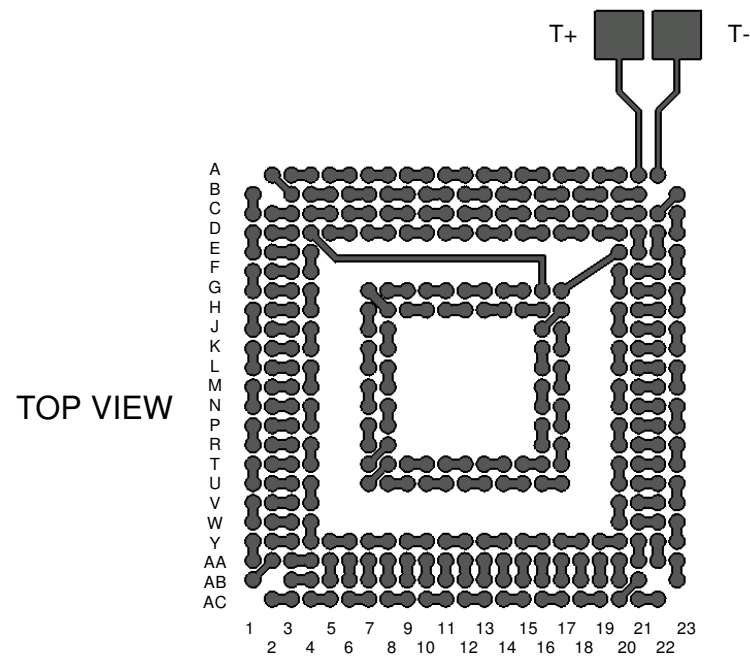
TOLERANCE UNLESS NOTED		APPROVALS		DATE	TopLine TITLE BGA368T.3C-DC238D DAISY CHAIN DUMMY				
X.X	+/- 0.10	DRAWN J. Hines		10/23/2011					
X.XX	+/- 0.05	ENG			SCALE 11.5:1		SIZE A	DRAWING NO. 532383	REV A
X.XXX	+/- 0.025	MFG			DO NOT SCALE DRAWING		SHEET 1 OF 2		
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION		REVISED					
ALL DIMENSIONS IN		<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS							



BALL VIEW

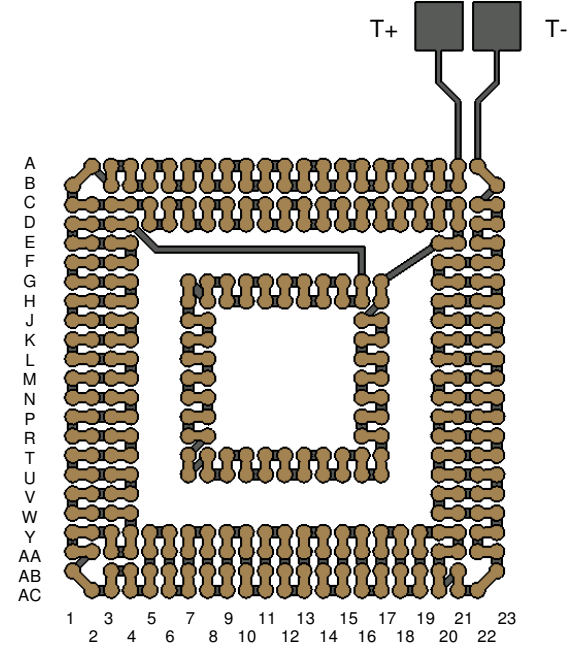


BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.24mm (9.5mil).
 - 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.15mm (5.9mil).
 - 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (7.8mil).

TopLine ®			
TITLE		BGA368T.3C-DC238D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
8.5:1	A	532383	A
DO NOT SCALE DRAWING			SHEET 2 OF 2